

**Electronic Filing System (EFS) Data**  
**Electronic Patent Application Submission**  
**USPTO Use Only**

EFS ID: 70292

Application ID: 10711897



Title of Invention:

METHOD AND STRUCTURE FOR  
IMPROVING CMOS DEVICE  
RELIABILITY USING  
COMBINATIONS OF INSULATING  
MATERIALS

First Named Inventor: Haining Yang

Domestic/Foreign Application: Domestic Application

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U.S. DEPARTMENT OF COMMERCE  
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FEE RECORD SHEET

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